
PRODUCT ADVISORY

Data Sheet Specification Correction for the Listed Intersil EPSOIC Packaged Products

**Refer to:
PA12030**

Date: May 2, 2012

May 2, 2012

To: Our Valued Intersil Customer

Subject: Data Sheet Specification Correction for the Listed Intersil EPSOIC Packaged Products

This advisory is to inform you that Intersil has made corrections to the POD (Package Outline Drawing) referenced in the data sheet specifications for the listed EPSOIC (Exposed Pad Small Outline Integrated Circuit) packaged products. The updates to the POD correct the package body width ("E") millimeter minimum and maximum dimensions, terminal length for soldering ("L") millimeter maximum dimension, and change the controlling dimension from millimeter to inches in Note 10. There have been no changes made to the package or product itself. The updated data sheets incorporating the corrected POD are available on the Intersil web site at <http://www.intersil.com/data/fn/fn9072.pdf>, <http://www.intersil.com/data/fn/fn9159.pdf>, and <http://www.intersil.com/data/fn/fn9205.pdf>.

Products affected:

HIP6601BECBZ	ISL6612AECBZ-TR5248	ISL6613AECBZ
HIP6601BECBZA	ISL6612AECBZ-TS2713	ISL6613AECBZ-T
HIP6601BECBZA-T	ISL6612AEIBZ	ISL6613AEIBZ
HIP6601BECBZ-T	ISL6612AEIBZ-T	ISL6613AEIBZ-T
HIP6603BECBZ	ISL6612BECBZ	ISL6613BECBZ
HIP6603BECBZ-T	ISL6612BECBZ-T	ISL6613BECBZ-T
ISL6612AECBZ	ISL6612BEIBZ	ISL6613BEIBZ
ISL6612AECBZ-T	ISL6612BEIBZ-T	ISL6613BEIBZ-T

Intersil will take all necessary actions to conform to agreed upon customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to continue receiving product processed to the same established conditions and systems used for manufacturing of material supplied today.

If you have concerns with this advisory, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,



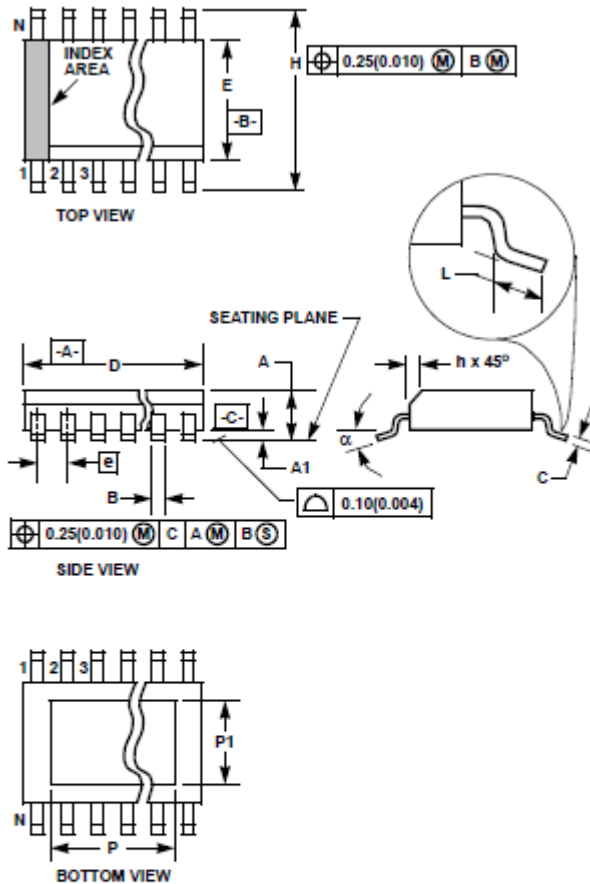
Jon Brewster
Intersil Corporation

PA12030

CC: J. Touvell R. Cruz M. Driscoll M. Kafi

Incorrect POD – PA12030

Small Outline Exposed Pad Plastic Packages (EPSONIC)



M8.15B

8 LEAD NARROW BODY SMALL OUTLINE EXPOSED PAD PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.056	0.068	1.43	1.68	-
A1	0.001	0.005	0.03	0.13	-
B	0.0138	0.0192	0.35	0.49	9
C	0.0075	0.0098	0.19	0.25	-
D	0.189	0.196	4.80	4.98	3
E	0.150	0.157	3.31	3.39	4
e	0.050 BSC		1.27 BSC		-
H	0.230	0.244	5.84	6.20	-
h	0.010	0.016	0.25	0.41	5
L	0.016	0.035	0.41	0.64	6
N	8		8		7
α	0°	8°	0°	8°	-
P	-	0.094	-	2.387	11
P1	-	0.094	-	2.387	11

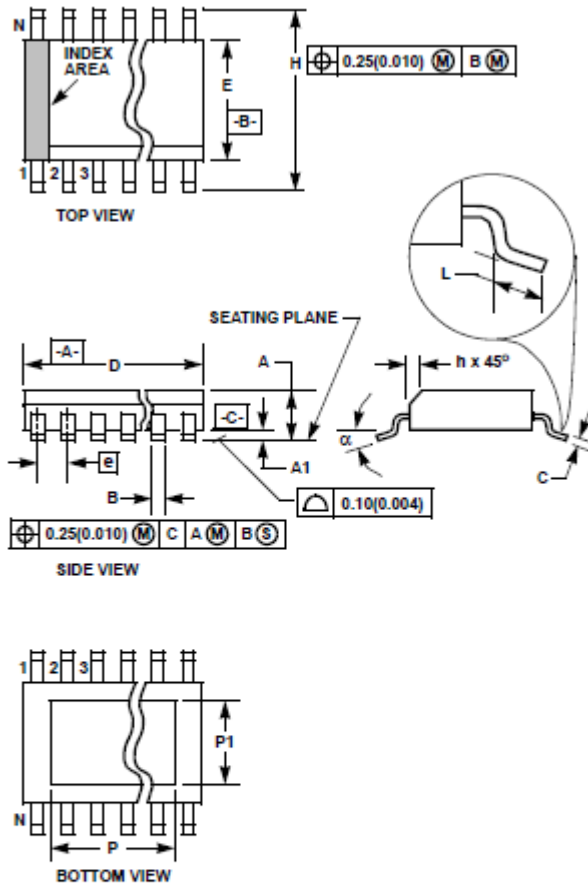
Rev. 3 6/05

NOTES:

1. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
4. Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
6. "L" is the length of terminal for soldering to a substrate.
7. "N" is the number of terminal positions.
8. Terminal numbers are shown for reference only.
9. The lead width "B", as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch).
10. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.
11. Dimensions "P" and "P1" are thermal and/or electrical enhanced variations. Values shown are maximum size of exposed pad within lead count and body size.

Correct POD – PA12030

Small Outline Exposed Pad Plastic Packages (EPSONIC)



M8.15B

8 LEAD NARROW BODY SMALL OUTLINE EXPOSED PAD
PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.056	0.066	1.43	1.68	-
A1	0.001	0.005	0.03	0.13	-
B	0.0138	0.0192	0.35	0.49	9
C	0.0075	0.0098	0.19	0.25	-
D	0.189	0.196	4.80	4.98	3
E	0.150	0.157	3.81	3.99	4
e	0.050 BSC		1.27 BSC		-
H	0.230	0.244	5.84	6.20	-
h	0.010	0.016	0.25	0.41	5
L	0.016	0.035	0.41	0.89	6
N	8		8		7
α	0°	8°	0°	8°	-
P	-	0.094	-	2.387	11
P1	-	0.094	-	2.387	11

Rev. 5 8/10

NOTES:

- Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
- Dimensioning and tolerancing per ANSI Y14.5M-1982.
- Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
- Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
- The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
- "L" is the length of terminal for soldering to a substrate.
- "N" is the number of terminal positions.
- Terminal numbers are shown for reference only.
- The lead width "B", as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch).
- Controlling dimension: INCH. Converted millimeter dimensions are not necessarily exact.
- Dimensions "P" and "P1" are thermal and/or electrical enhanced variations. Values shown are maximum size of exposed pad within lead count and body size.